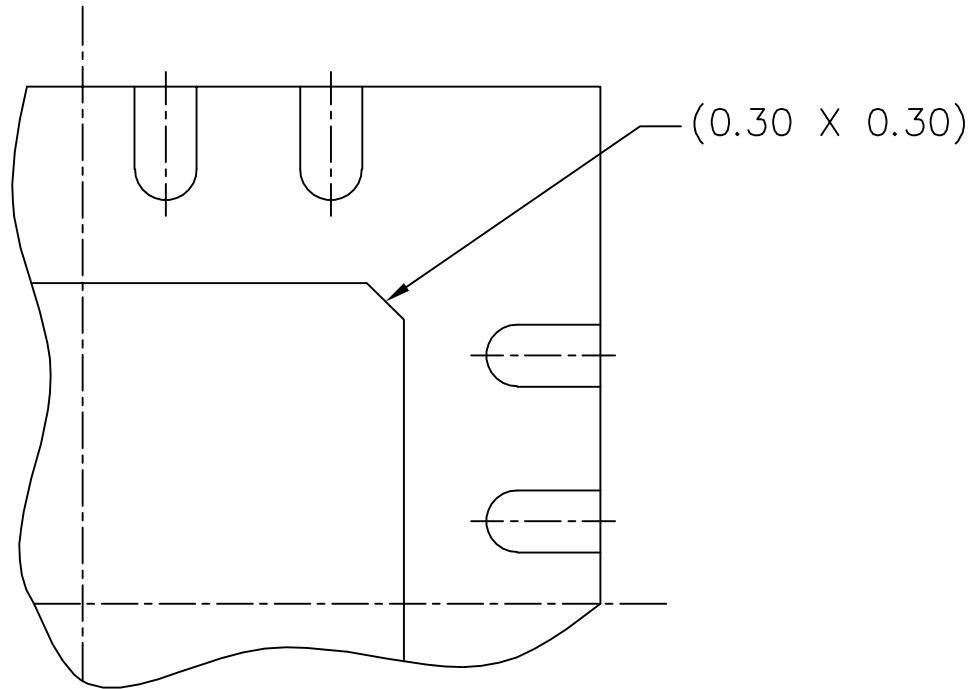
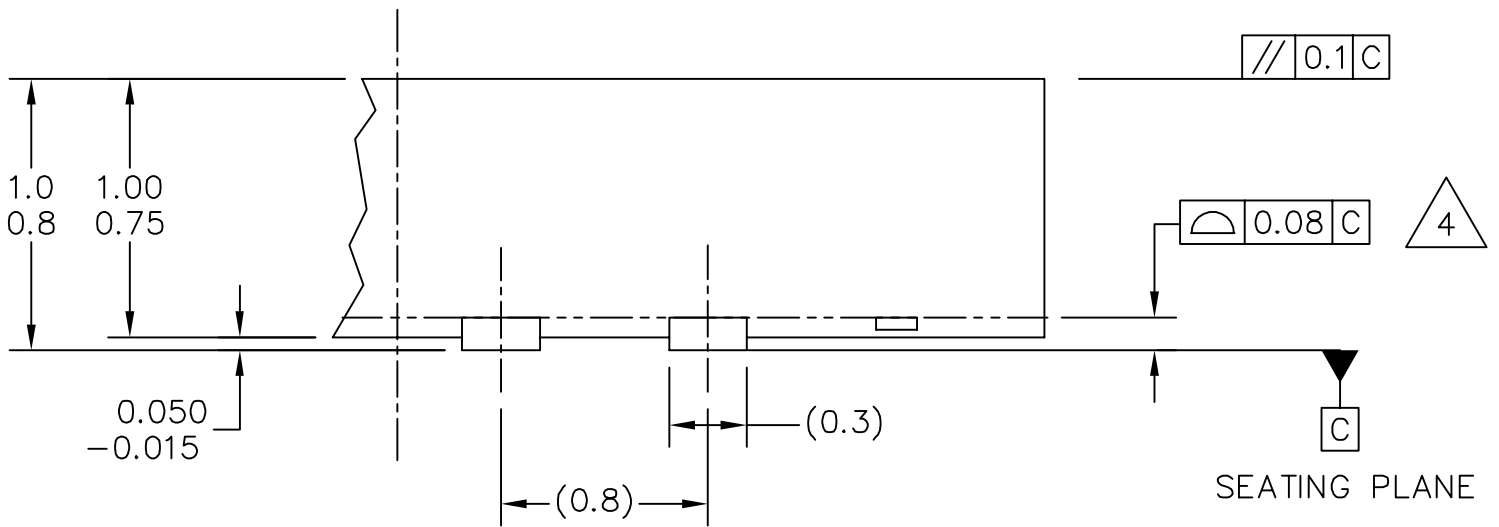


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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 16 TERMINAL, 0.8 PITCH (5 X 5 X 1) CASE OUTLINE	DOCUMENT NO: 98ARE10614D	REV: 0	
	CASE NUMBER: 1679-01	23 MAR 2005	
	STANDARD: FREESCALE		




DETAIL M  
PIN 1 BACKSIDE IDENTIFIER



DETAIL G  
VIEW ROTATED 90° CW

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	CASE NUMBER: 1679-01	23 MAR 2005	
	STANDARD: FREESCALE		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2MM.

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